

有铅

Sn50/Pb50 SnPbBi

- 1 0.4mm
- 2 12
- 3
- 4
- 5
- 6 --- PCB
- 7 ICT
- 8 Paste in hole

		ROL1	J-STD-004
		0.2wt%	
(SIR)		1 10 ¹³	25mil
		1 10 ¹²	40 90%RH 96Hrs
		1 10 ⁵	
			IPC-TM-650
			IPC-TM-650
			In house
		85~91wt% ± 0.5	
		9~15wt% ± 0.5	
		200 Pa.s ±10% Malcolm (10rpm,2)	T3,90% metal for printing
		80 Pa.s ±10% Malcolm (10rpm,2)	T4,87% metal for syringe
		0.55 ± 0.05	In house
		90%	Copper plate(Sn63,90% metal)
			J-STD-005
			In house
Vs	48gF	0	IPC-TM-650 ± 5%
	56gF	2	
	68gF	4	
	44gF	8	
		12	In house
			0~10



1

T3 mesh -325/+500 25~45 m

Fine pitch

2

1) “ ”

0~10

200

4

2)

3

1 ;

(适当的搅拌时间因搅拌方式、装置及环境温度等因素而有所不同，应在事前多做试验来确定)。

3



有铅免洗

0.4mm

0.12mm



有铅免洗

80%

	60 ~ 90HS
	45 ⁰ ~ 60 ⁰
	2 ~ 4 10 ⁵ pa
	20 ~ 40mm/sec 15 ~ 20mm/sec 50 ~ 100mm/sec
	25 ± 3 40 ~ 70%



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*

*

PCB

PCB

A5

200g

B5

300g

A4

400g

4

4

5

6

此有铅



500g

PE

20

35



0 ~10

•

•

0

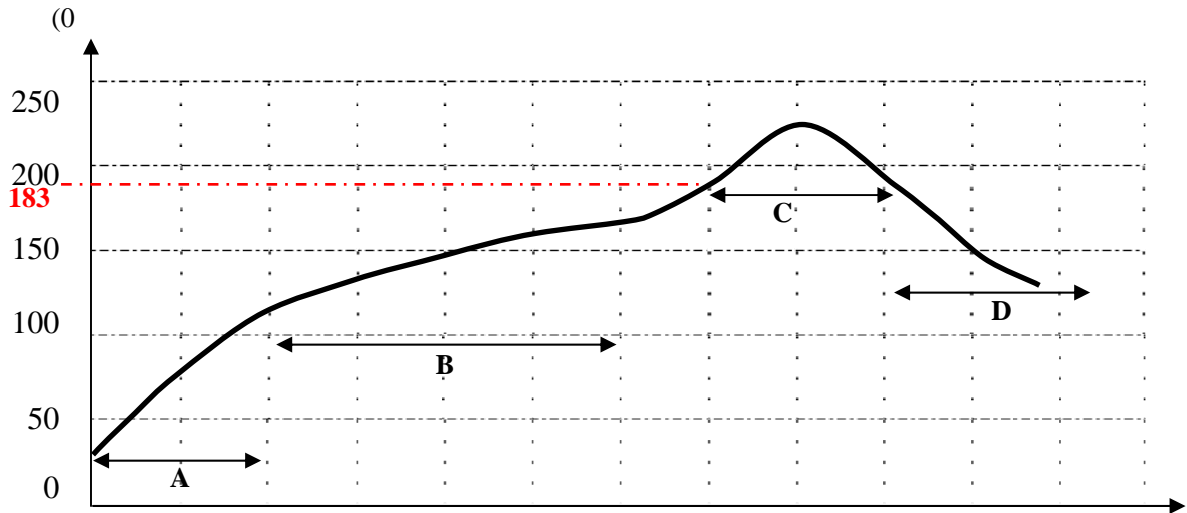
6



MSDS

有铅

Sn50/Pb50 SnPbBi



A. _____ 25~33%

* 1.0~3.0 /
*

B. _____ 33~50%

* _____ PCB _____ 1.5 /
* 150~200 60~90

C. _____

* 230~245 183 70~90 Important 200 50~65
*
*

D. _____

* 4 75
*
*

